

FIG.1

| Atmospheric environment Zone | | I | | II | | III | | IV | | V | |
|---------------------------------|-----------------------------------|-------------------|---------------------|-------------------|---------------------|-------------------|---------------------|-------------------|---------------------|-------------------|---------------------|
| Environmental factors | | Measured value | Evaluation point | Measured value | Evaluation point | Measured value | Evaluation point | Measured value | Evaluation point | Measured value | Evaluation point |
| Temperature(°C) | A | ≤20 | 1 | ≤25 | 2 | ≤30 | 4 | ≤35 | 8 | >35 | 12 |
| | B | ≤60 | 1 | ≤65 | 6 | ≤70 | 12 | ≤80 | 24 | >80 | 36 |
| | SO ₂ | ≤0.02 | 1 | ≤0.05 | 4 | ≤0.2 | 8 | ≤0.5 | 16 | >0.5 | 24 |
| | H ₂ S | ≤0.02 | 1 | ≤0.05 | 6 | ≤0.2 | 12 | ≤0.5 | 24 | >0.5 | 36 |
| | NO ₂ | ≤0.02 | 1 | ≤0.05 | 3 | ≤0.2 | 6 | ≤0.5 | 12 | >0.5 | 18 |
| Corrosive gas (mdd) | Cl ⁻ | ≤0.02 | 1 | ≤0.05 | 7 | ≤0.2 | 14 | ≤0.5 | 28 | >0.5 | 42 |
| | NH ₃ | ≤0.02 | 1 | ≤0.1 | 3 | ≤1.0 | 6 | ≤10 | 12 | >10 | 18 |
| | Sea salt particle (mdd) | ≤0.01 | 1 | ≤0.03 | 5 | ≤0.1 | 10 | ≤0.3 | 20 | >0.3 | 30 |
| Sea salt particle | D | >2.0 | | ≥1.5 | | ≥1.0 | | ≥0.5 | | <0.5 | |
| | Distance from coast (km) | | | | | | | | | | |

FIG.2

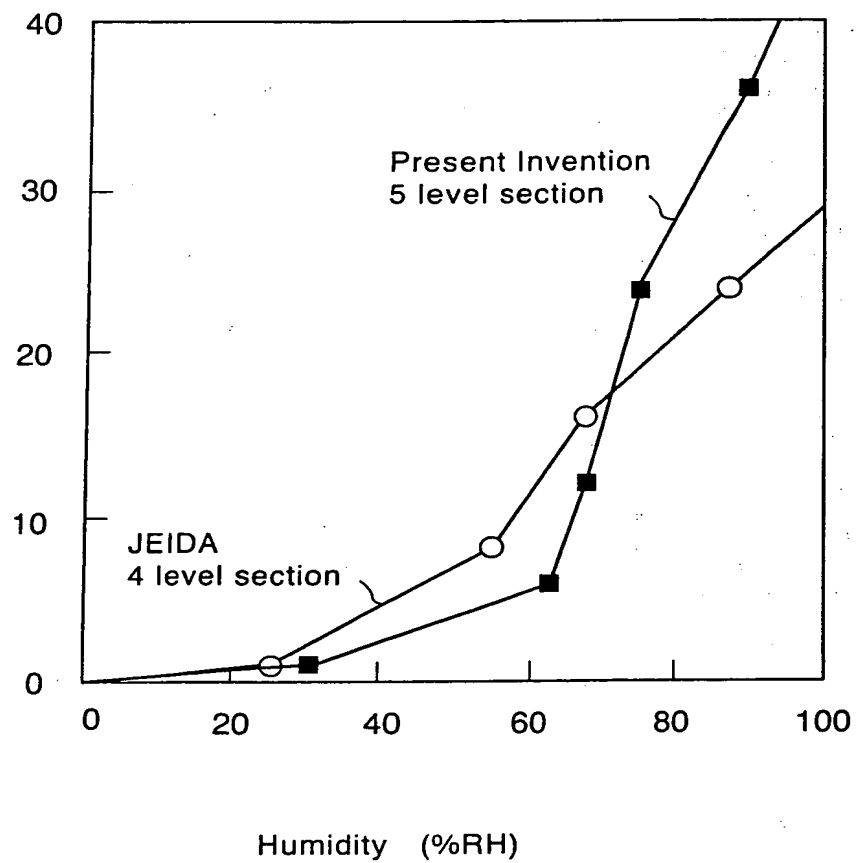


FIG.3

JEIDA-29-1990 Dividing into four stage classes

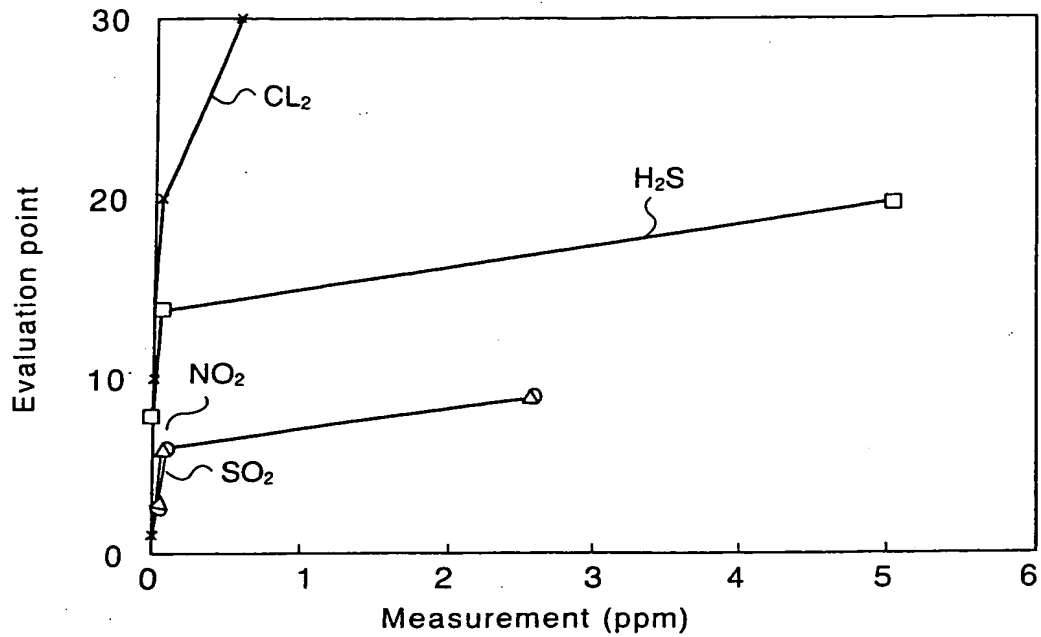


FIG.4A

Present invention Dividing into five point classes

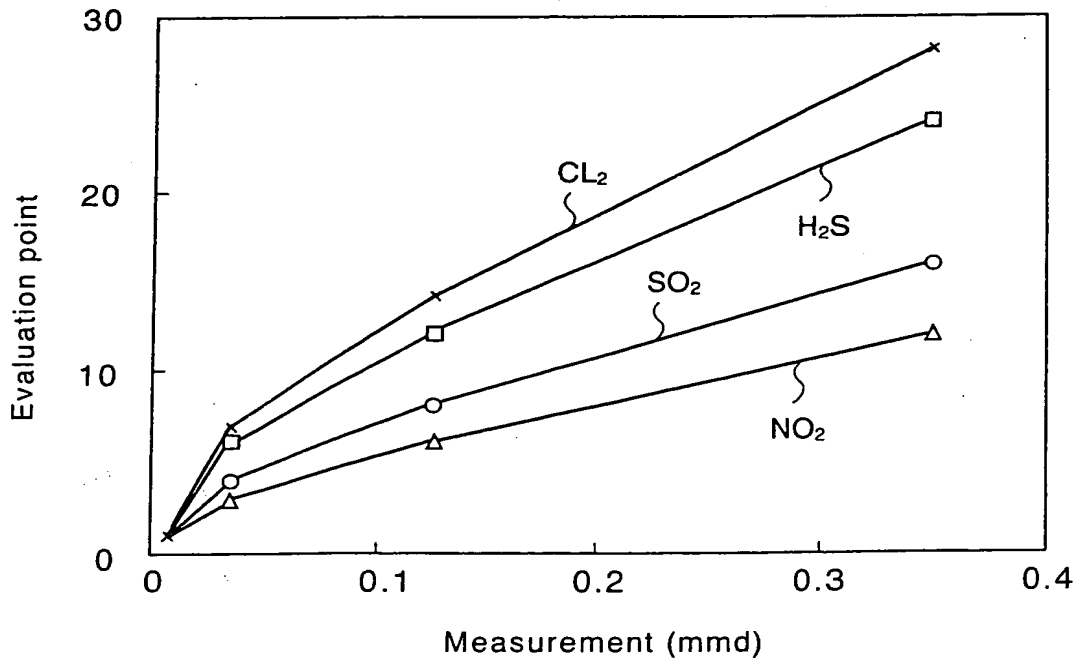


FIG.4B

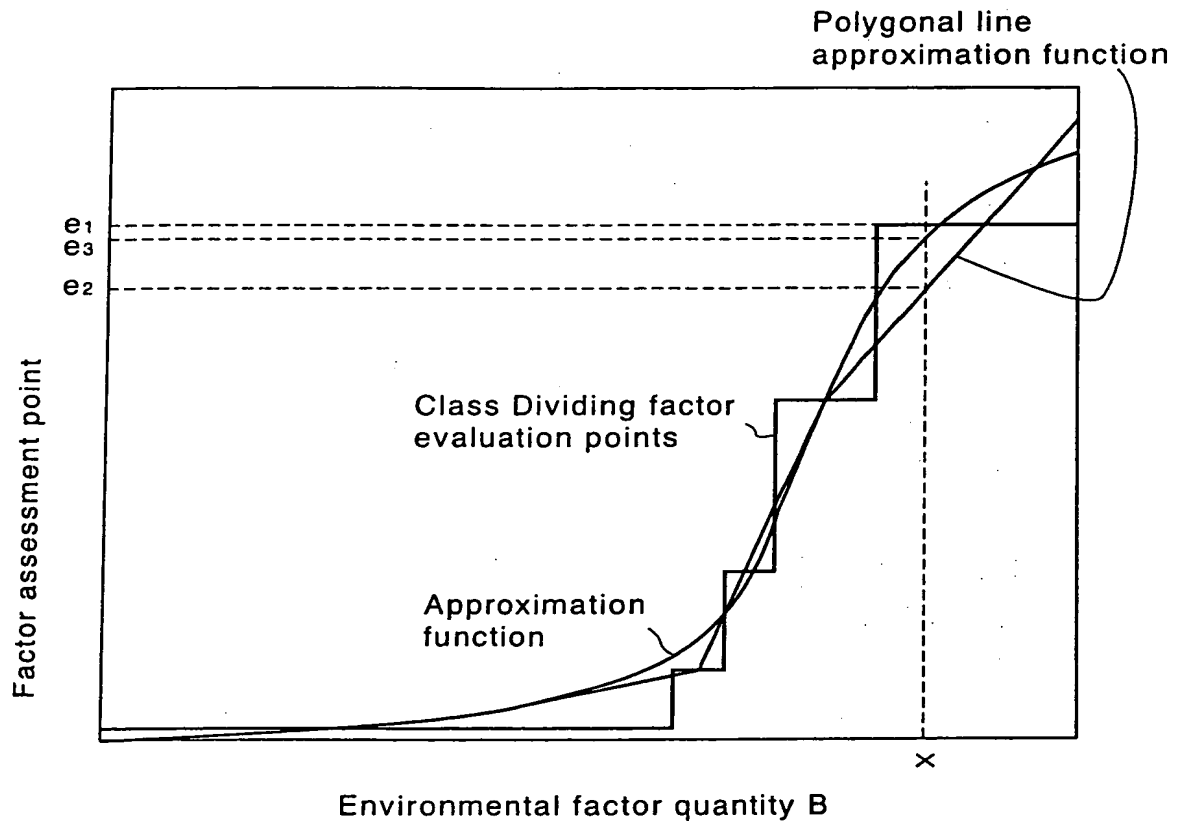


FIG.5

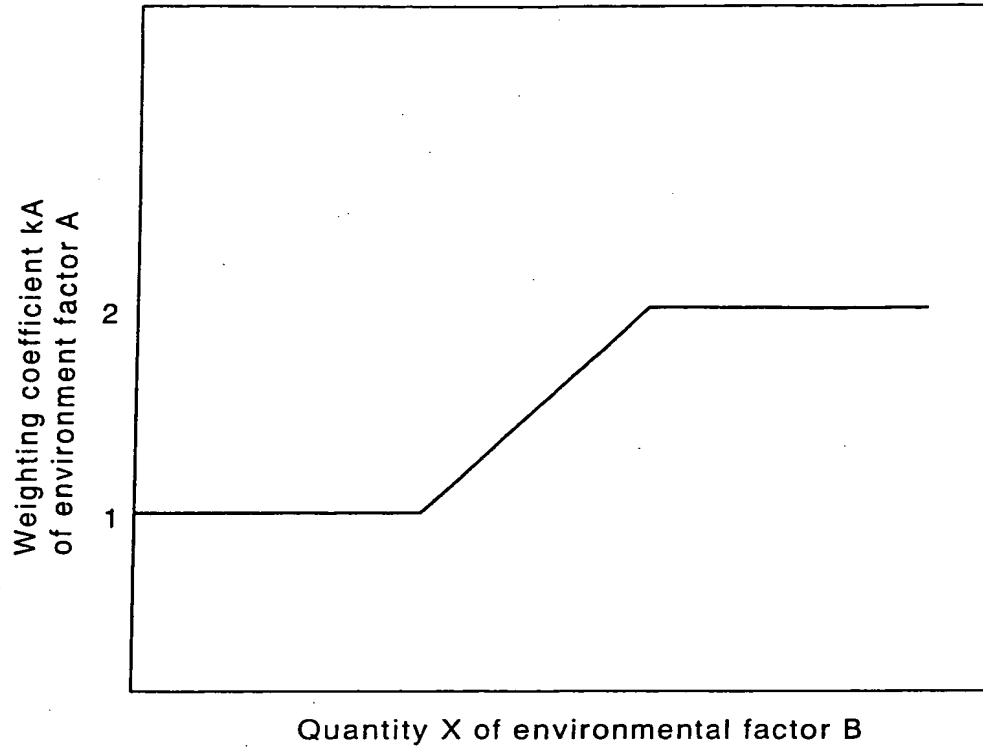


FIG. 6

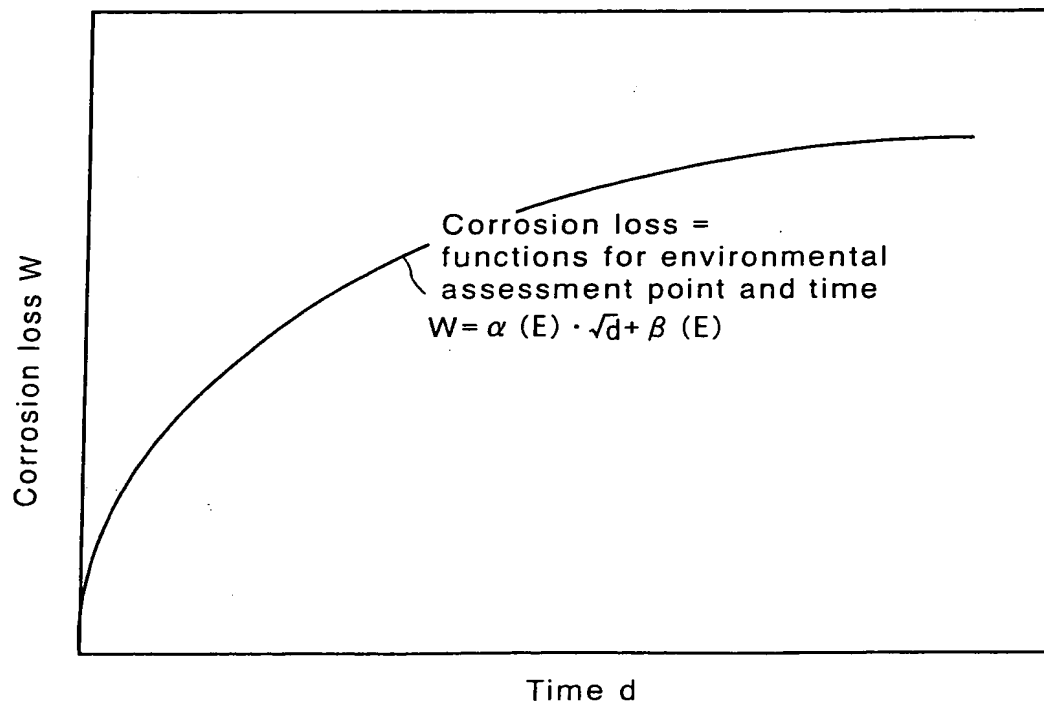


FIG. 7

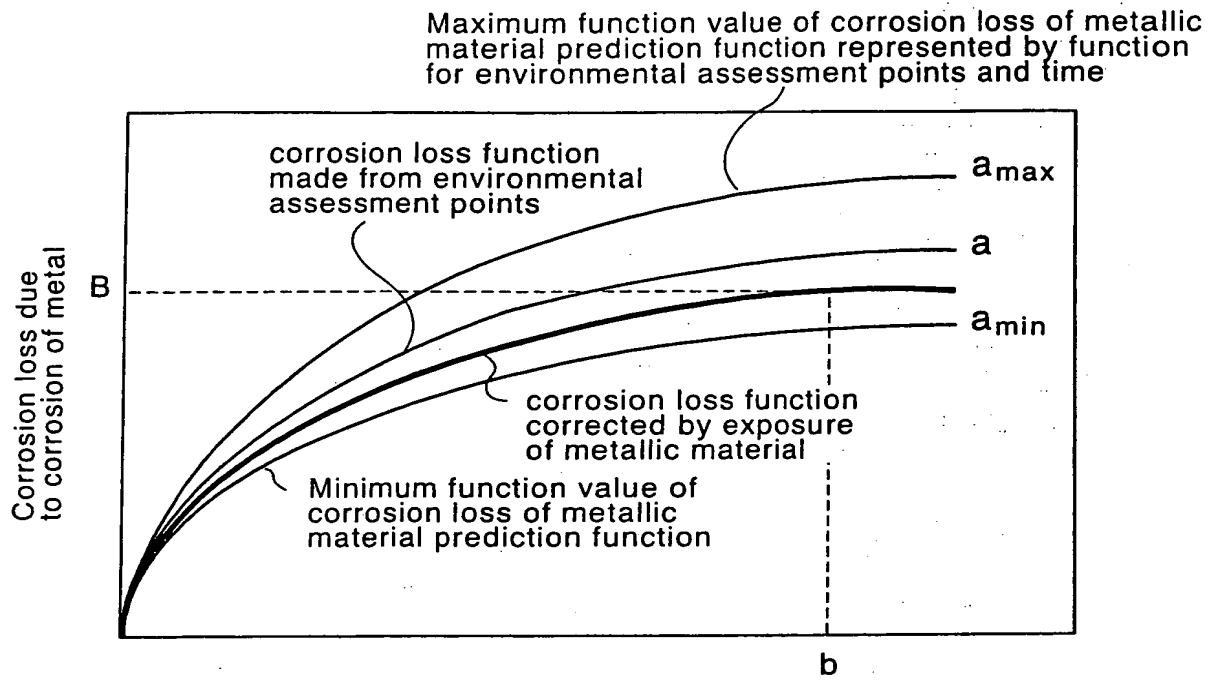


FIG.8

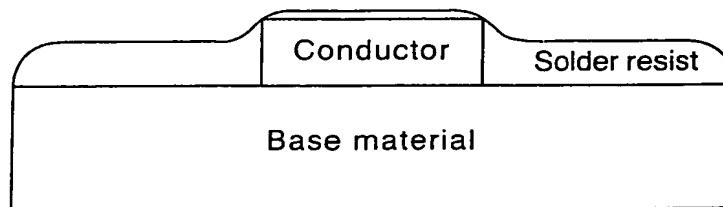
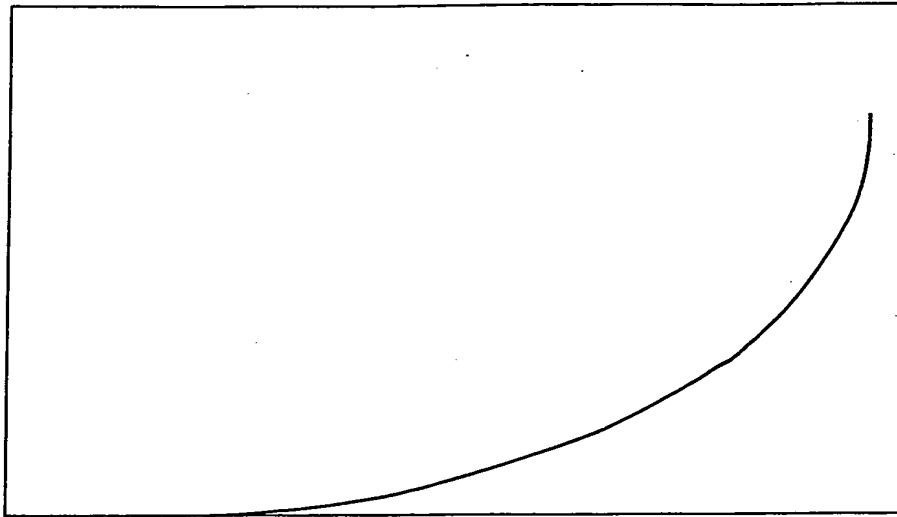


FIG.9

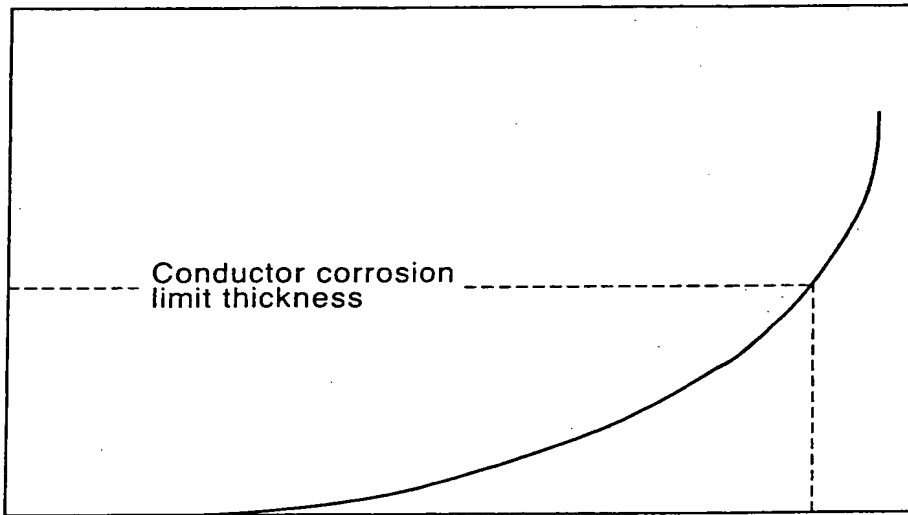
Thickness of corrosion of a conductor



Amount of corroded copper

FIG.10A

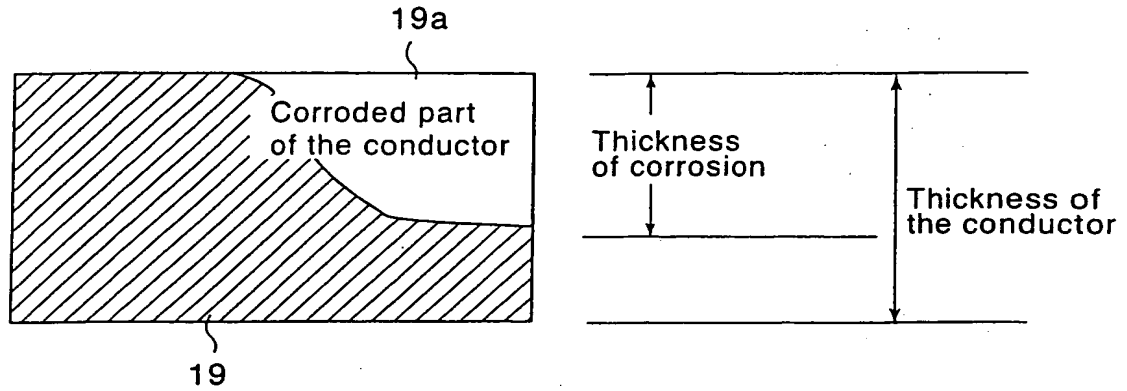
Thickness of corrosion of a conductor



Amount of corroded copper

Limit for an amount of corrosion

FIG.10B



$$\text{Corrosion loss rate} = (\text{thickness of corrosion} / \text{thickness of the conductor}) \times 100$$

FIG.11

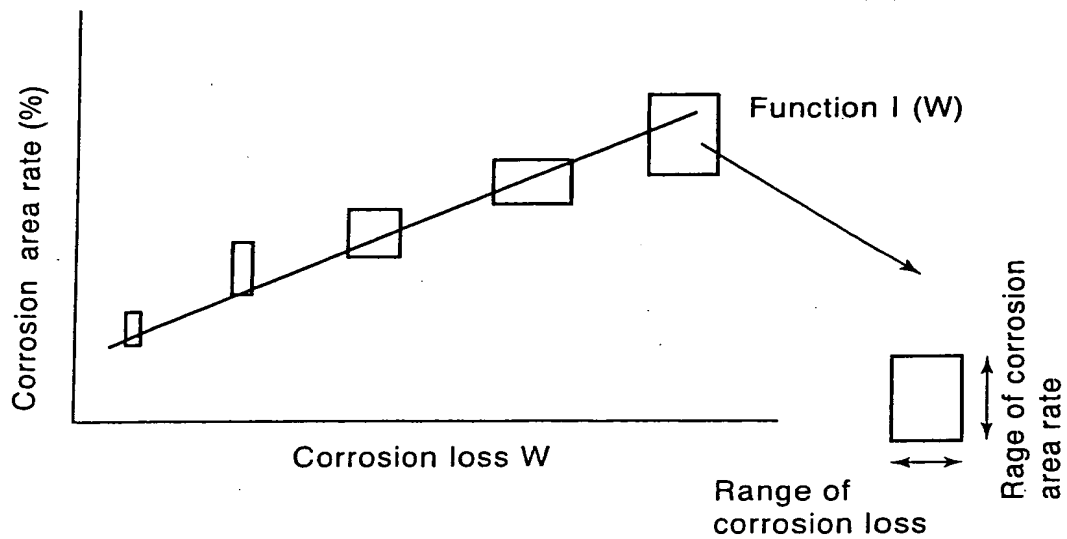


FIG.12

| IC type | Year | Manufacturer | Sealing resin | Chip protective film | Other... | Correlation function(W) |
|---------|------|--------------|-------------------|----------------------|----------|-------------------------|
| IC1 | 1982 | T Inc. | Epoxy blend--- | PSG | | $I_1(W)$ |
| IC2 | 1979 | N Inc. | Epoxy blend--- | None | | $I_2(W)$ |
| IC3 | 1992 | T Inc. | Epoxy blend--- | SIN | | $I_3(W)$ |
| ... | ... | ... | ... | ... | ... | ... |

FIG.13

| IC type | Year | Manufacturer | Sealing resin | Chip protective film | Other... | Change of time sequence of aluminium wiring corrosion area rate $U_i = h_i(t)$ Correlation function $F(u)$ of aluminium wiring corrosion area rate and faults |
|---------|------|--------------|-----------------------|----------------------|----------|--|
| IC1 | 1982 | T Inc. | Epoxy blend--- | PSG | | $U_1=m_1(t), F_1=n_1(u)$ |
| IC2 | 1979 | N Inc. | Epoxy blend--- | None | | $U_2=m_2(t), F_2=n_2(u)$ |
| IC3 | 1992 | H Inc. | polyimide blend--- | SiN | | $U_3=m_3(t), F_3=n_3(u)$ |
| ... | ... | ... | ... | ... | ... | ... |

FIG.14

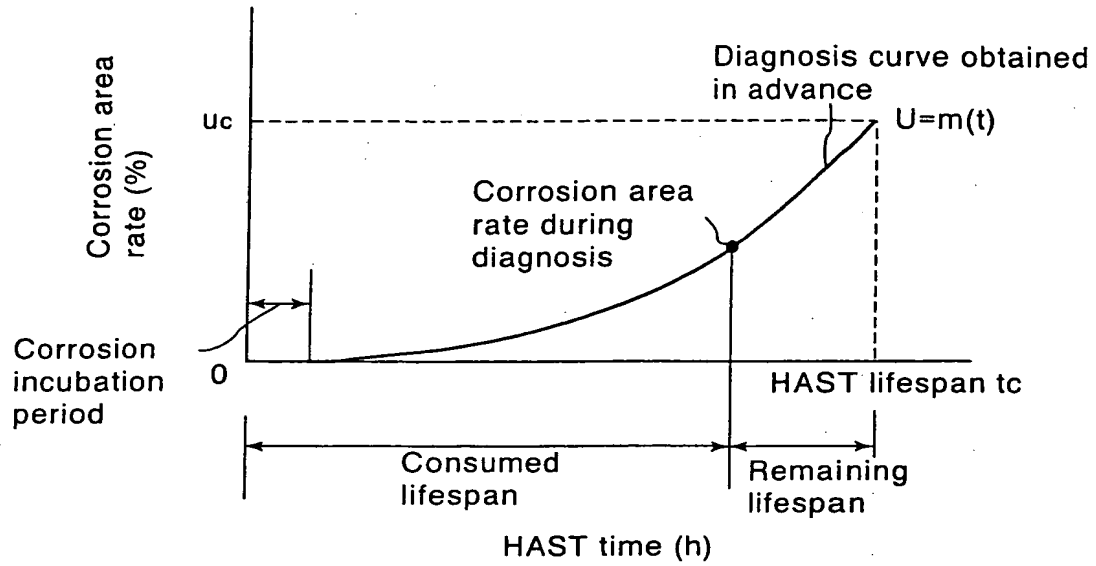


FIG.15

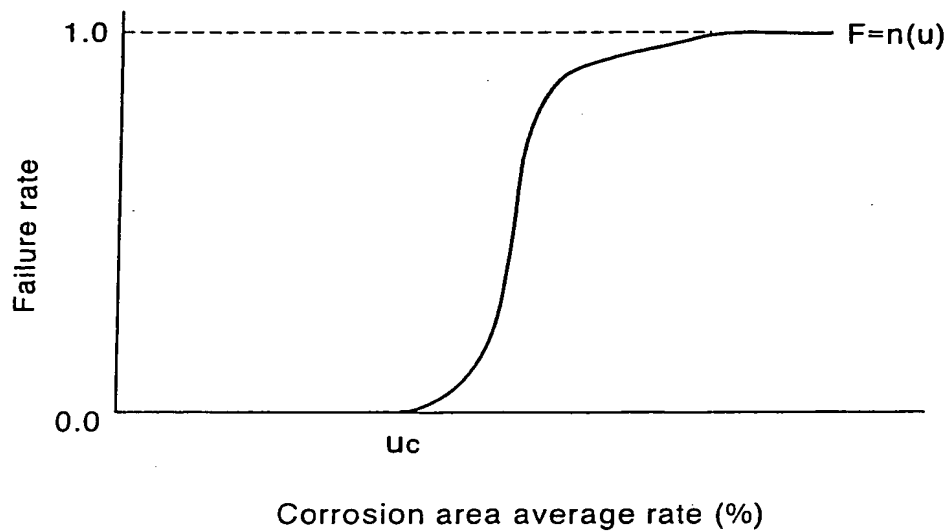


FIG.16

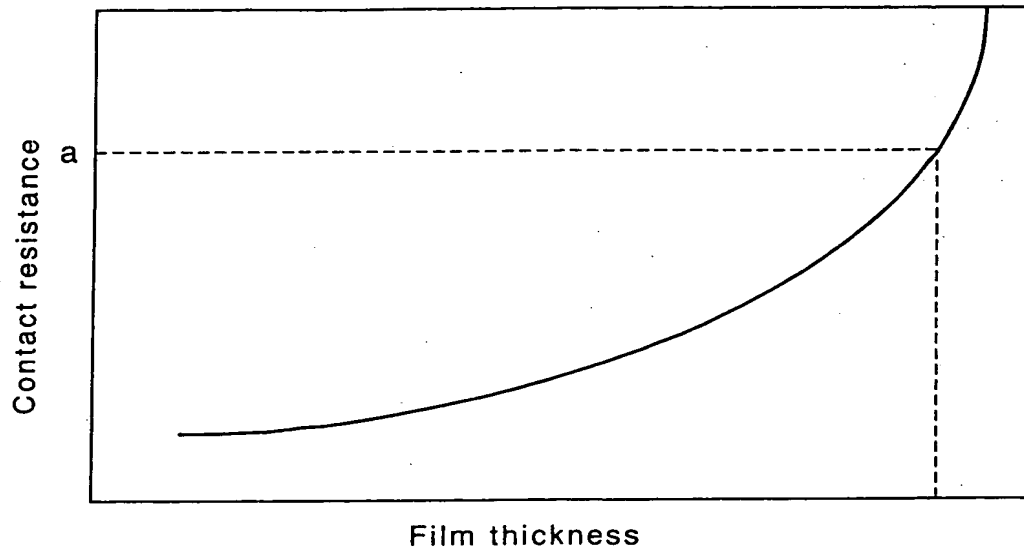


FIG.17

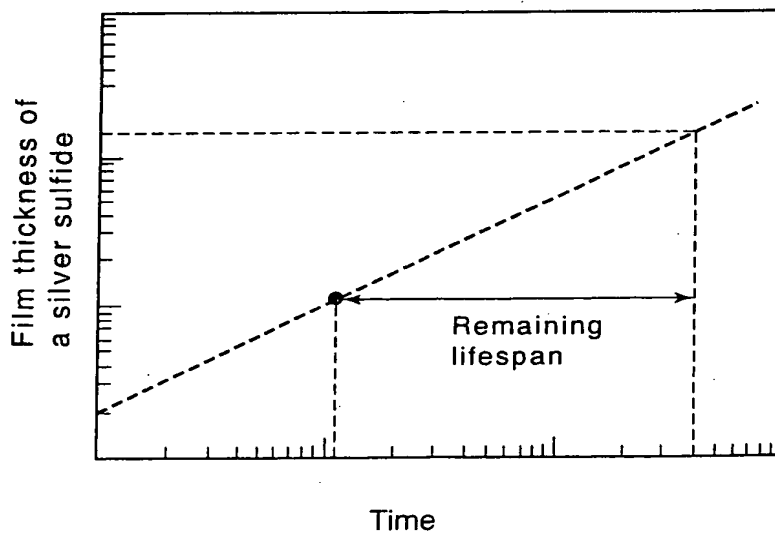


FIG.18

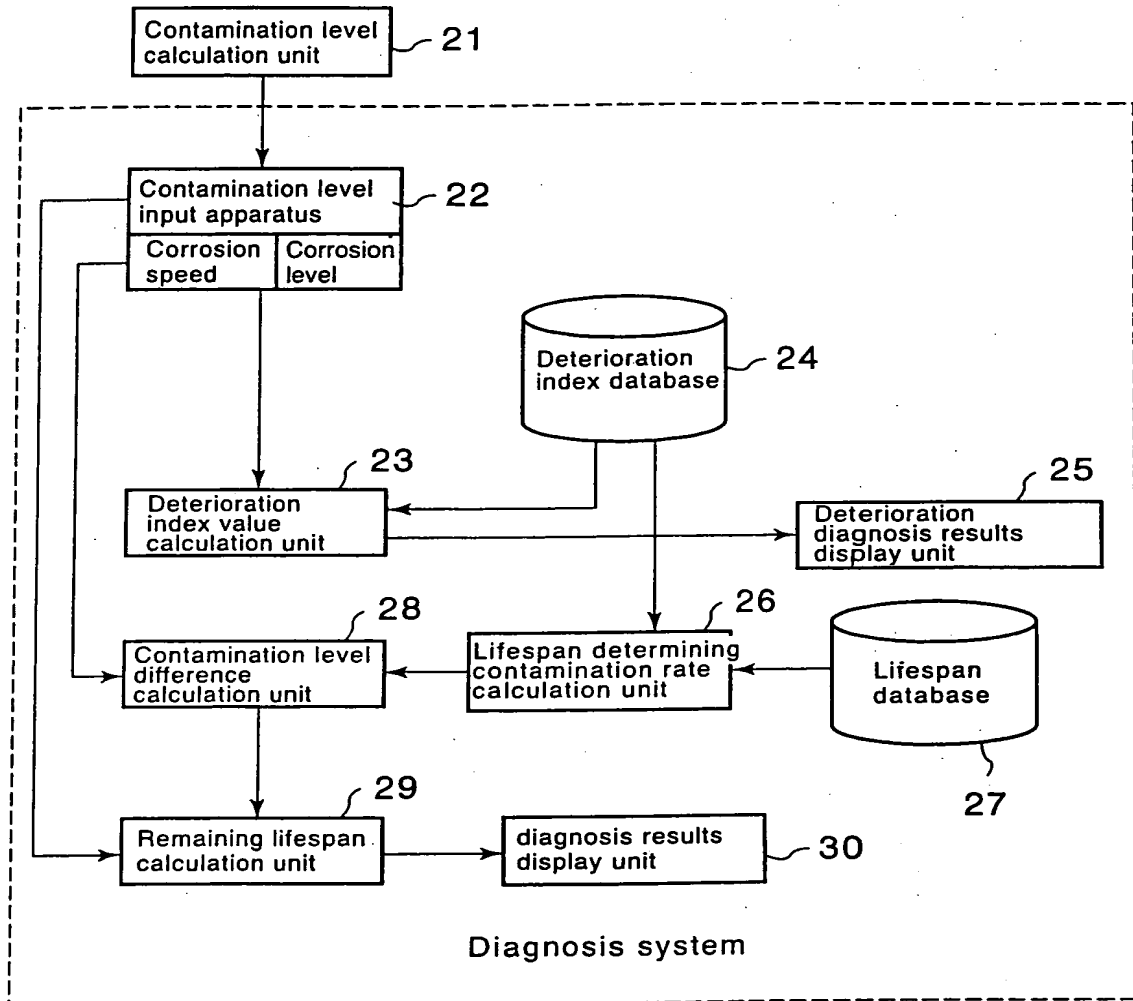


FIG.19

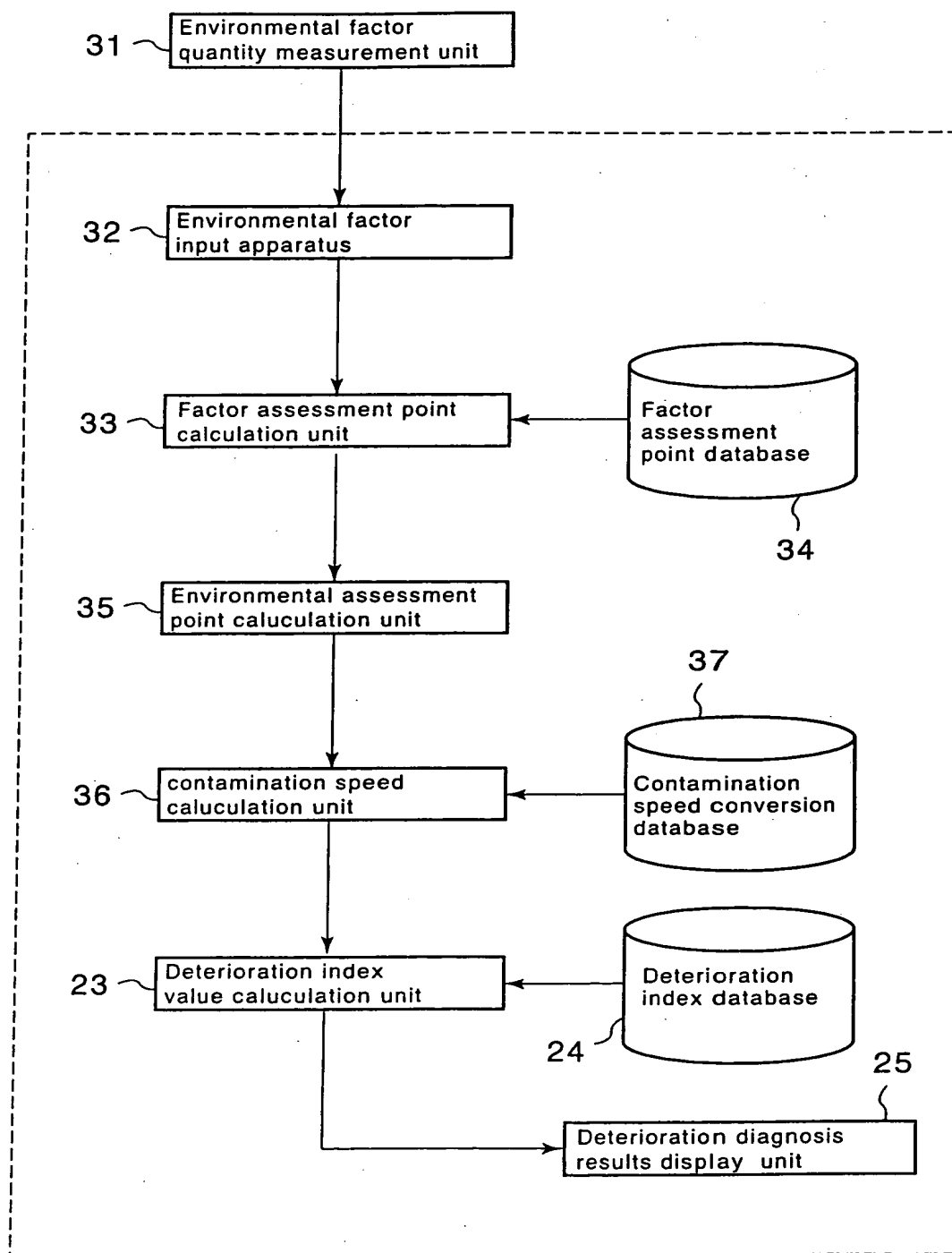


FIG.20

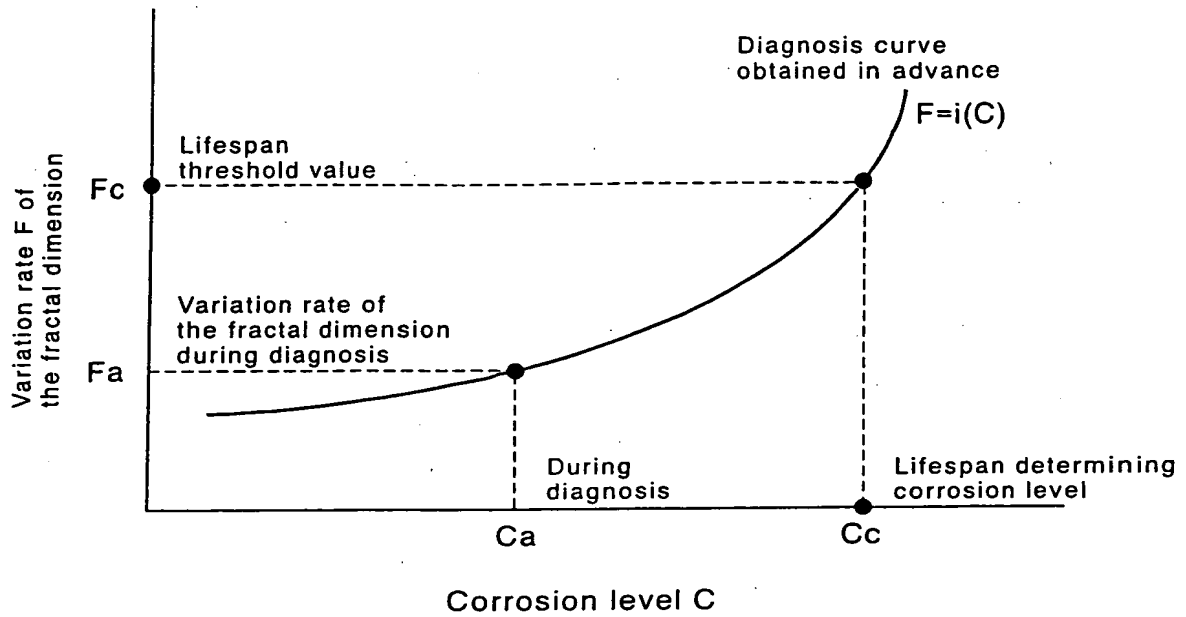


FIG.21

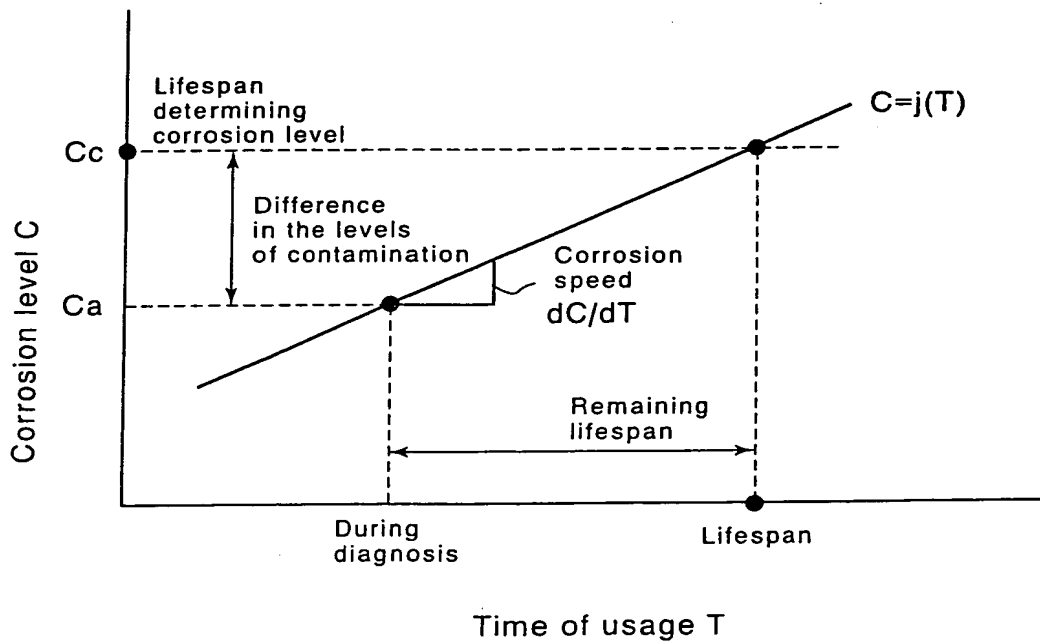


FIG.22

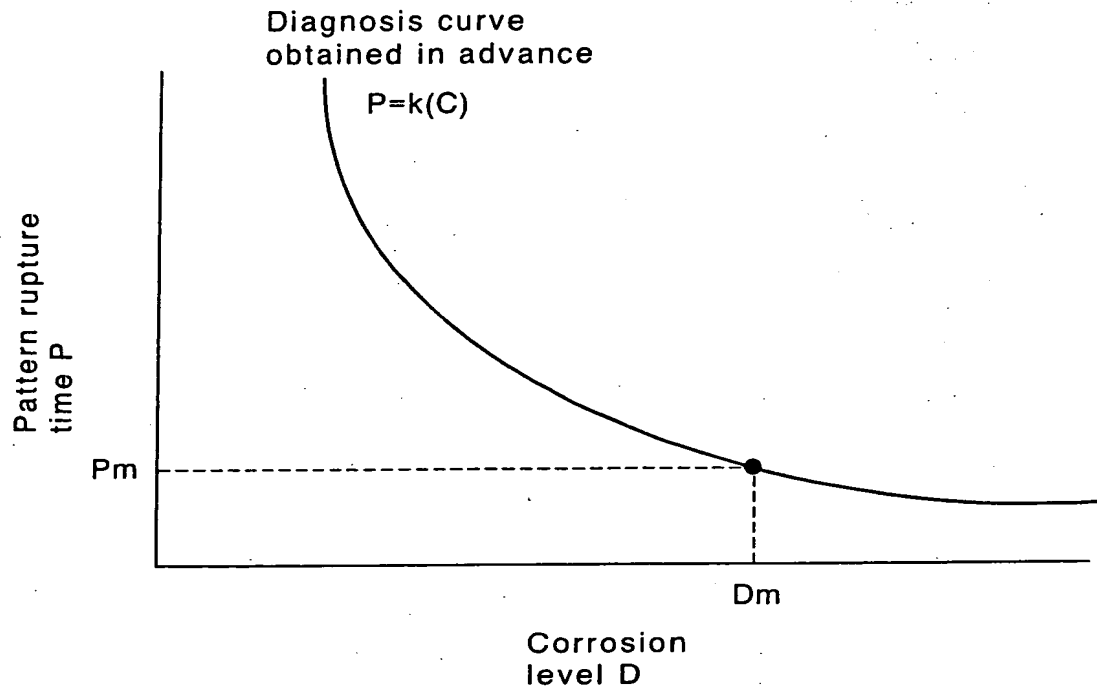


FIG.23

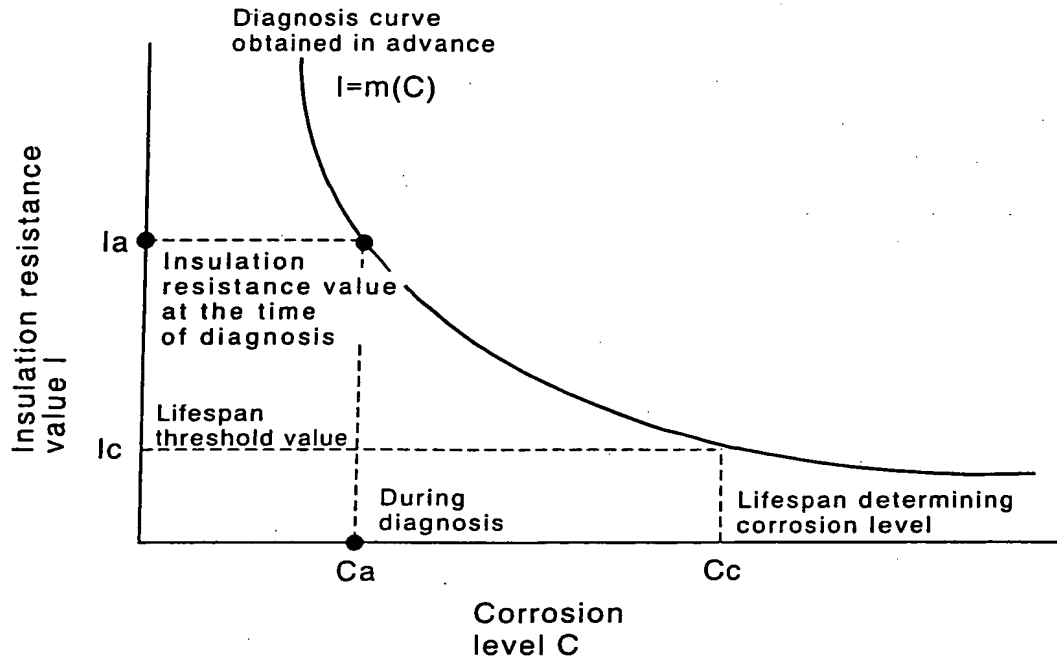


FIG. 24

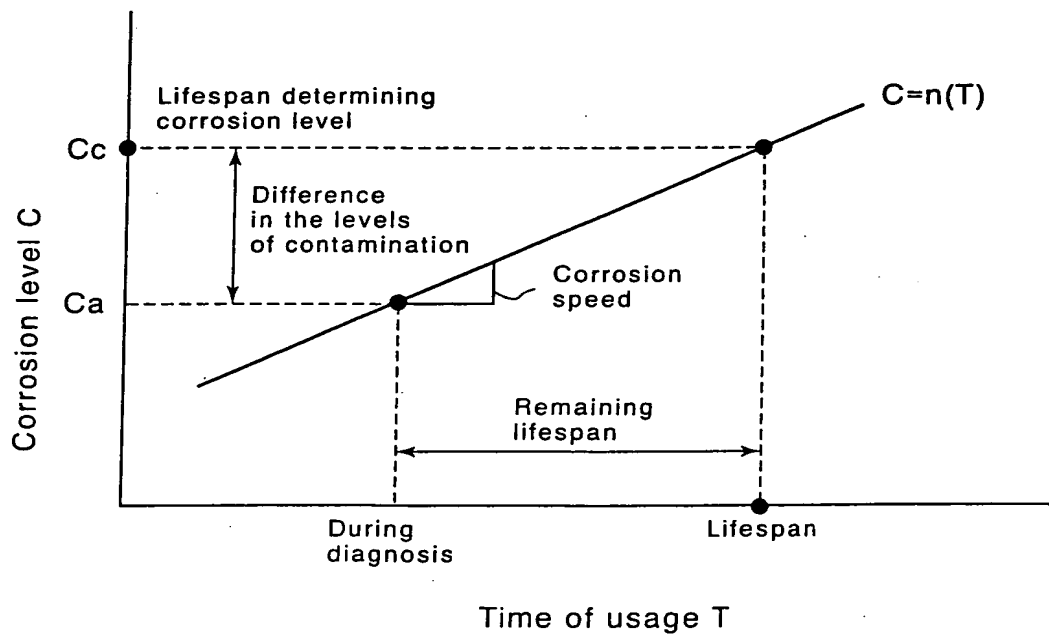


FIG. 25